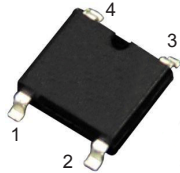


2A SURFACE MOUNT SCHOTTKY BRIDGE



MBF

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

Features

- Low profile package
- Ideal for automated placement
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability

Mechanical Date

- **Case:** MBF Molded plastic body over Schottky barrier chips
- **Terminals:** Solderable per MIL-STD-750, Method 2026
- **Approx. Weight:** 75mg 0.0026oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Items	Symbol	KMB24F	KMB26F	KMB28F	KMB210F	KMB220F	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	40	60	80	100	200	V
Maximum RMS voltage	V _{RMS}	28	42	56	70	140	V
Maximum DC blocking voltage	V _{DC}	40	60	80	100	200	V
Maximum average forward output rectified current at T _A =30℃	I _{F(AV)}	2.0					A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50		40			A
Maximum Forward Voltage per leg at 2.0 A	V _F	0.55	0.70	0.85			V
Maximum DC Reverse Current T _J =25℃ at Rated DC Blocking Voltage T _J =100℃	I _R	0.5 10		0.3 5			mA
Typical Junction Capacitance (Note1)	C _j	220	80				pF
Typical Thermal Resistance (Note2)	R _{θJA}	75					℃/W
Operating junction temperature range	T _J	-55 to +125					℃
Storage temperature range	T _{STG}	-55 to +125					℃

Note : 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

RATINGS AND CHARACTERISTICS CURVES (TA = 25 °C unless otherwise noted)

Fig.1 Forward Current Derating Curve

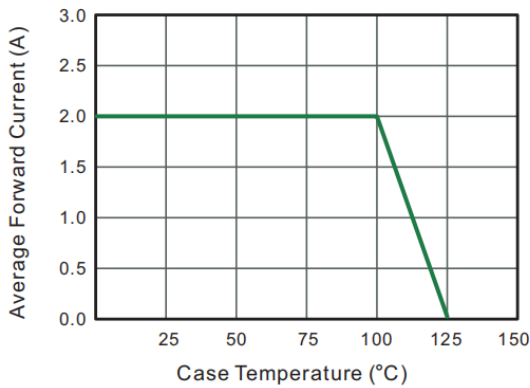


Fig.2 Typical Reverse Characteristics

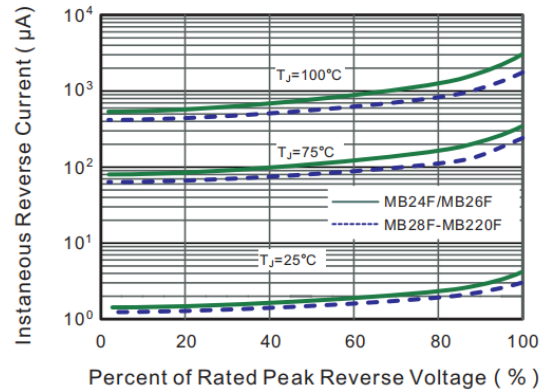


Fig.3 Typical Forward Characteristic

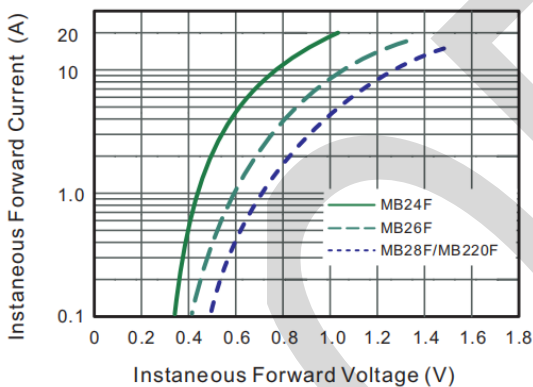


Fig.4 Typical Junction Capacitance

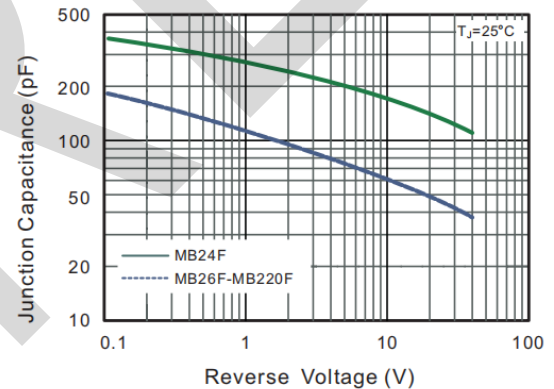


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

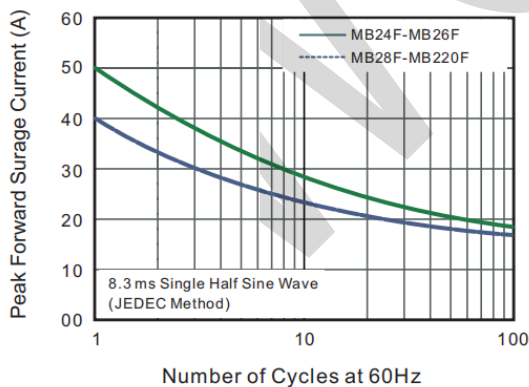
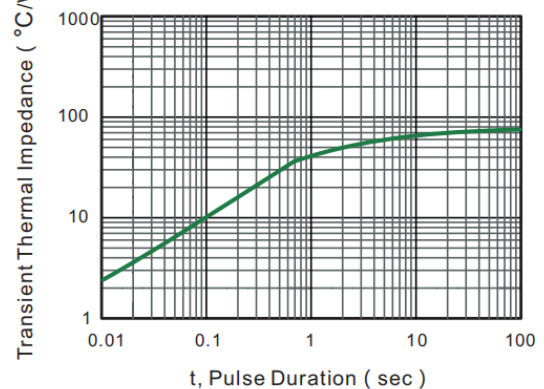
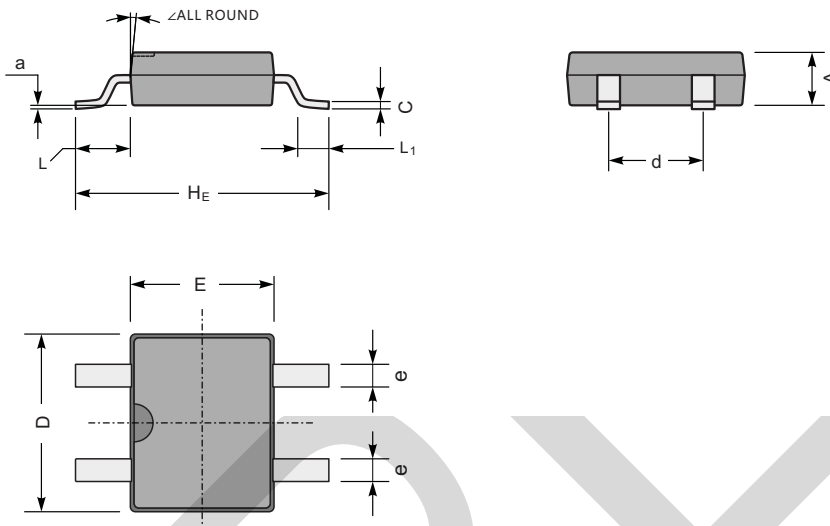


Fig.6 Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS



MBF mechanical data

UNIT		A	C	D	E	H_E	d	e	L	L_1	a	$\angle$
mm	max	1.6	0.22	5.0	4.1	7.0	2.7	0.8	1.7	1.1	0.2	7°
	min	1.2	0.15	4.5	3.6	6.4	2.3	0.5	1.3	0.5	—	
mil	max	63	8.7	197	161	276	106	31	67	43	8	
	min	47	5.9	177	142	252	91	20	51	20	—	

The recommended mounting pad size

